



THE UNITED STATES PATENT AND TRADEMARK OFFICE

2814

In re the Application of:

Norio FUKASAWA et al

Serial Number: 09/029,608

Group Art Unit: 2814

Filed: May 15, 1998

Examiner: Graybill, D.

For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE AND METHOD FOR MOUNTING THE DEVICE

AMENDMENT TRANSMITTAL

Commissioner for Patents
Washington, D.C. 20231

July 30, 2001

Sir:

Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below:

	CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional Fee
Total Claims	42	50	=	0	X \$9	X \$18	
Independent Claims	19	17	=	2	X \$40	X \$80	160.00
## First Presentation of Multiple Dependent Claims					\$135	270	
TOTAL FEES ENCLOSED:							\$160.00

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X Enclosed please find our check in the amount of **\$160.00** for the additional claims fee in connection with this amendment. The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. 01-2340. Two duplicates of this sheet are attached.

Respectfully submitted,
ARMSTRONG, WESTERMAN, HATTORI,
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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

July 30, 2001

Sir:

In response to the Office Action dated April 30, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 54-64, 70-77, 79-85 and non-elected claims 103-107 without prejudice or disclaimer.

Please add new claims 109-131 as follows:

109. A semiconductor device comprising:
a semiconductor element having a surface on which protruding electrodes are formed;
a resin layer formed on the surface of the semiconductor element so as to seal the protruding electrodes except end portions thereof; and